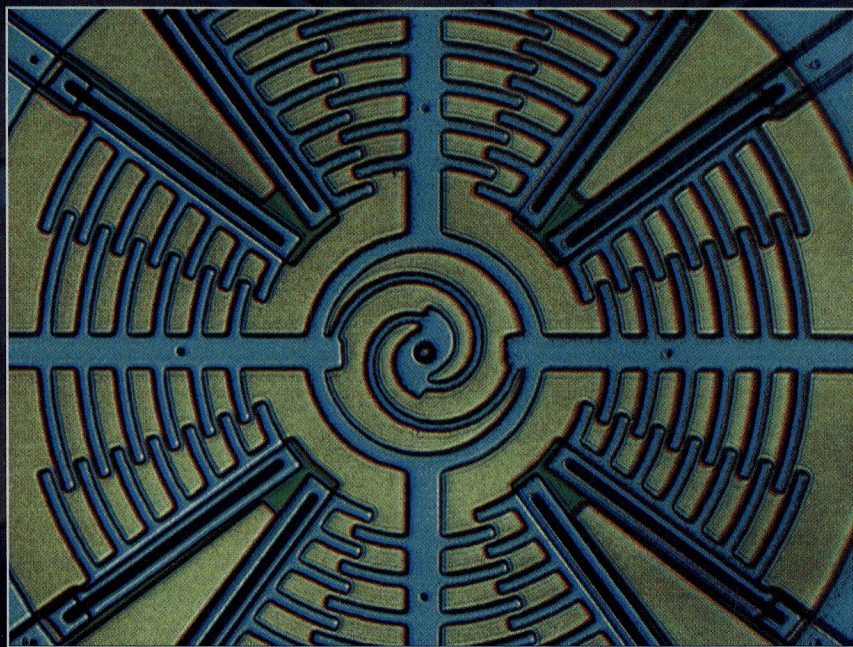




A GUIDE TO Hands-on MEMS Design and Prototyping

Joel A. Kubby

CAMBRIDGE

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